

## E Series Power MOSFET

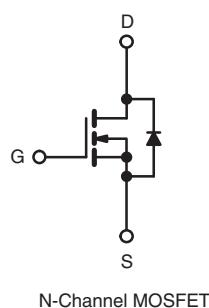
PRODUCT SUMMARY	
V <sub>DS</sub> (V) at T <sub>J</sub> max.	650
R <sub>DS(on)</sub> max. at 25 °C (Ω)	V <sub>GS</sub> = 10 V 0.039
Q <sub>g</sub> max. (nC)	362
Q <sub>gs</sub> (nC)	48
Q <sub>gd</sub> (nC)	98
Configuration	Single

### FEATURES

- Low figure-of-merit (FOM) R<sub>on</sub> x Q<sub>g</sub>
- Low input capacitance (C<sub>iss</sub>)
- Reduced switching and conduction losses
- Ultra low gate charge (Q<sub>g</sub>)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT  
**HALOGEN**  
**FREE**



### APPLICATIONS

- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Renewable energy
  - Solar (PV inverters)

### ORDERING INFORMATION

Package	TO-247AD
Lead (Pb)-free and Halogen-free	SiHW73N60E-GE3

### ABSOLUTE MAXIMUM RATINGS (T<sub>C</sub> = 25 °C, unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V <sub>DS</sub>	600	V
Gate-Source Voltage	V <sub>GS</sub>	± 30	
Continuous Drain Current (T <sub>J</sub> = 150 °C)	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 25 °C	A
		T <sub>C</sub> = 100 °C	
Pulsed Drain Current <sup>a</sup>	I <sub>DM</sub>	73	A
Linear Derating Factor		46	
Single Pulse Avalanche Energy <sup>b</sup>	E <sub>AS</sub>	236	mJ
Maximum Power Dissipation	P <sub>D</sub>	4.2	
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	520	W
Drain-Source Voltage Slope	V <sub>DS</sub> = 0 V to 80 % V <sub>DS</sub>	-55 to +150	°C
Reverse Diode dV/dt <sup>d</sup>	dV/dt	60	V/ns
Soldering Recommendations (Peak Temperature) <sup>c</sup>	for 10 s	8.4	
		300	°C

#### Notes

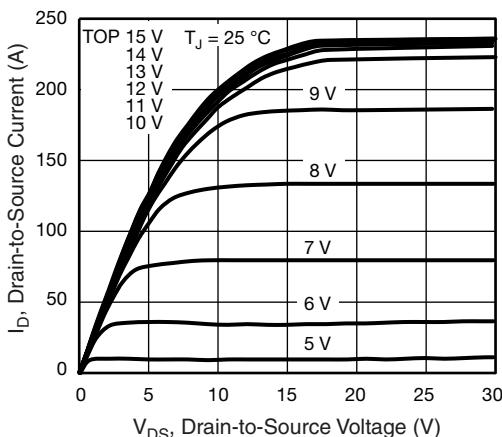
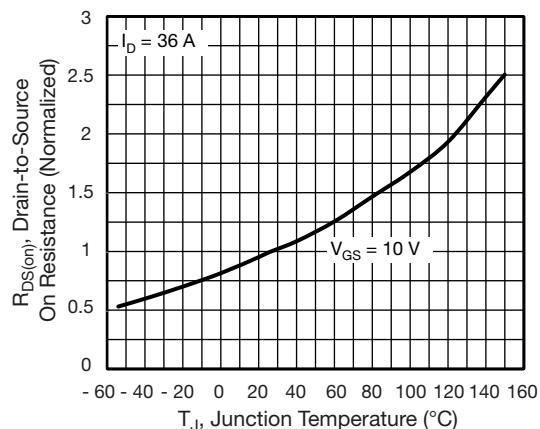
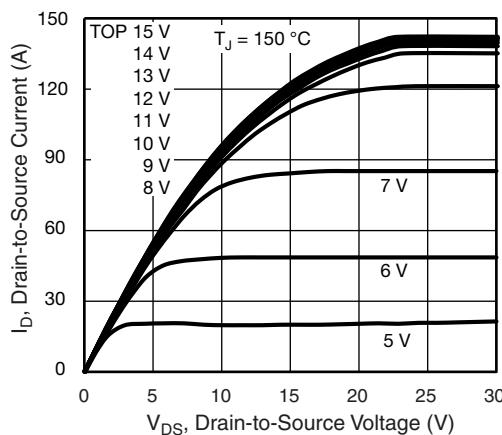
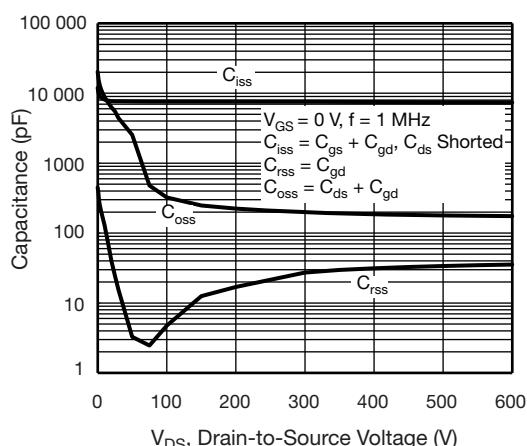
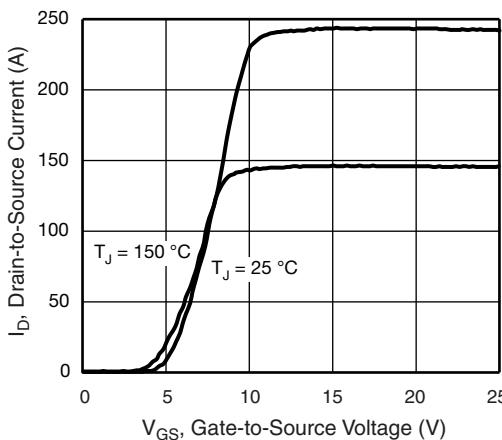
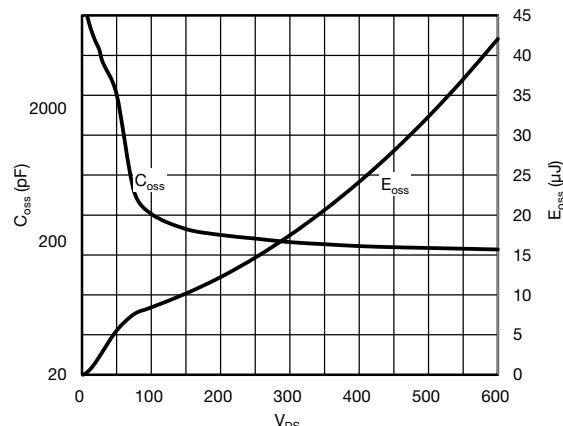
- Repetitive rating; pulse width limited by maximum junction temperature.
- V<sub>DD</sub> = 50 V, starting T<sub>J</sub> = 25 °C, L = 28.2 mH, R<sub>g</sub> = 25 Ω, I<sub>AS</sub> = 12 A.
- 1.6 mm from case.
- I<sub>SD</sub> ≤ I<sub>D</sub>, dI/dt = 30 A/μs, starting T<sub>J</sub> = 25 °C.

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	$R_{thJA}$	-	40	
Maximum Junction-to-Case (Drain)	$R_{thJC}$	-	0.24	°C/W

SPECIFICATIONS ( $T_J = 25$ °C, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
<b>Static</b>							
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0$ V, $I_D = 250$ μA		600	-	-	V
$V_{DS}$ Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to 25 °C, $I_D = 250$ μA		-	0.65	-	V/°C
Gate-Source Threshold Voltage (N)	$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = 250$ μA		2	-	4	V
Gate-Source Leakage	$I_{GSS}$	$V_{GS} = \pm 20$ V		-	-	± 100	nA
		$V_{GS} = \pm 30$ V		-	-	± 1	μA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 600$ V, $V_{GS} = 0$ V		-	-	1	
		$V_{DS} = 480$ V, $V_{GS} = 0$ V, $T_J = 125$ °C		-	-	10	μA
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = 10$ V	$I_D = 36$ A	-	0.032	0.039	Ω
Forward Transconductance	$g_{fs}$	$V_{DS} = 40$ V, $I_D = 10$ A		-	12	-	S
<b>Dynamic</b>							
Input Capacitance	$C_{iss}$	$V_{GS} = 0$ V, $V_{DS} = 100$ V, $f = 1$ MHz		-	7700	-	pF
Output Capacitance	$C_{oss}$			-	320	-	
Reverse Transfer Capacitance	$C_{rss}$			-	5	-	
Effective Output Capacitance, Energy Related <sup>a</sup>	$C_{o(er)}$	$V_{DS} = 0$ V to 480 V, $V_{GS} = 0$ V		-	259	-	
Effective Output Capacitance, Time Related <sup>b</sup>	$C_{o(tr)}$			-	907	-	
Total Gate Charge	$Q_g$			-	241	362	nC
Gate-Source Charge	$Q_{gs}$	$V_{GS} = 10$ V	$I_D = 24$ A, $V_{DS} = 480$ V	-	48	-	
Gate-Drain Charge	$Q_{gd}$			-	98	-	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 480$ V, $I_D = 24$ A, $V_{GS} = 10$ V, $R_g = 10$ Ω		-	63	95	ns
Rise Time	$t_r$			-	105	158	
Turn-Off Delay Time	$t_{d(off)}$			-	290	435	
Fall Time	$t_f$			-	120	180	
Gate Input Resistance	$R_g$	$f = 1$ MHz, open drain		-	1.52	-	Ω
<b>Drain-Source Body Diode Characteristics</b>							
Continuous Source-Drain Diode Current	$I_S$	MOSFET symbol showing the integral reverse p - n junction diode		-	-	73	A
Pulsed Diode Forward Current	$I_{SM}$			-	-	200	
Diode Forward Voltage	$V_{SD}$	$T_J = 25$ °C, $I_S = 36$ A, $V_{GS} = 0$ V		-	0.9	1.2	V
Reverse Recovery Time	$t_{rr}$	$T_J = 25$ °C, $I_F = I_S = 24$ A, $dl/dt = 100$ A/μs, $V_R = 25$ V		-	657	1314	ns
Reverse Recovery Charge	$Q_{rr}$			-	14.6	29.2	μC
Reverse Recovery Current	$I_{RRM}$			-	34.7	-	A

**Notes**

a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ .  
b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ .

**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)

**Fig. 1 - Typical Output Characteristics**

**Fig. 4 - Normalized On-Resistance vs. Temperature**

**Fig. 2 - Typical Output Characteristics**

**Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage**

**Fig. 3 - Typical Transfer Characteristics**

**Fig. 6 -  $C_{oss}$  and  $E_{oss}$  vs.  $V_{DS}$**

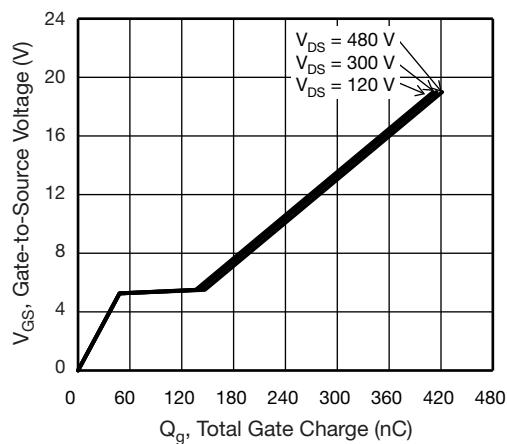


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

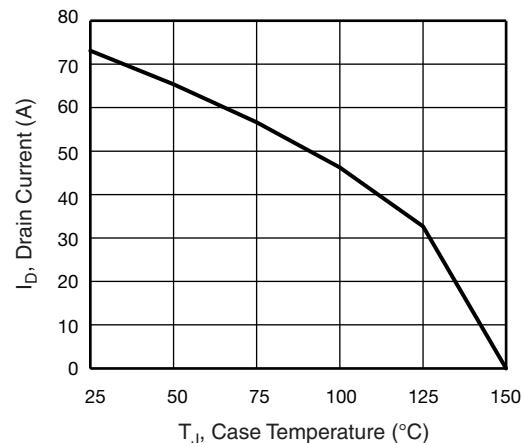


Fig. 10 - Maximum Drain Current vs. Case Temperature

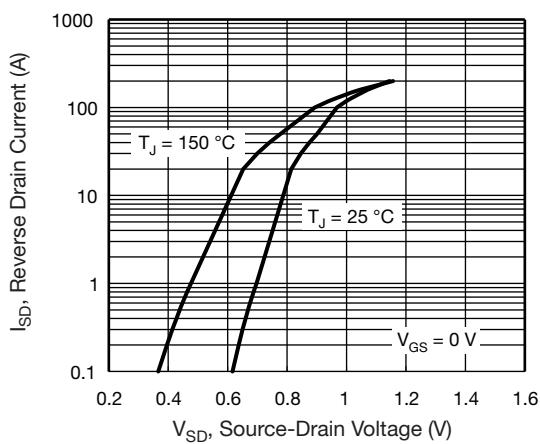


Fig. 8 - Typical Source-Drain Diode Forward Voltage

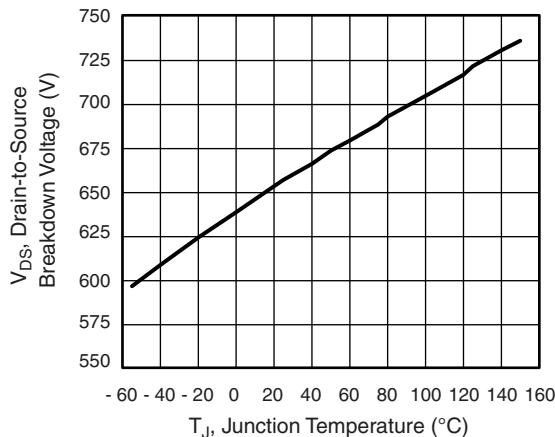


Fig. 11 - Temperature vs. Drain-to-Source Voltage

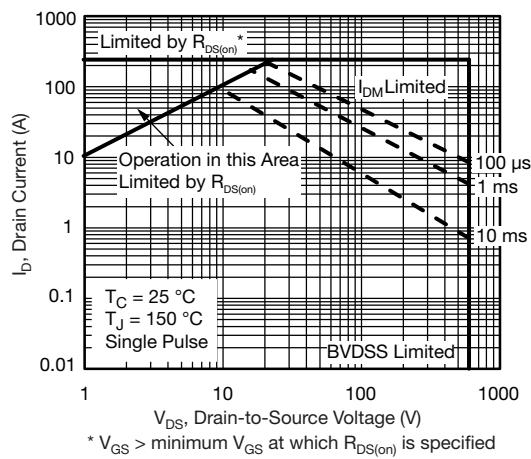
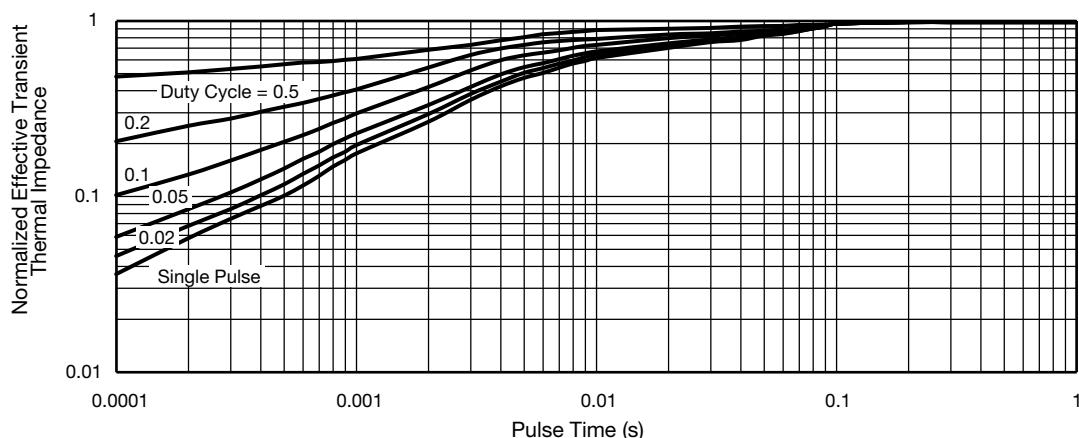
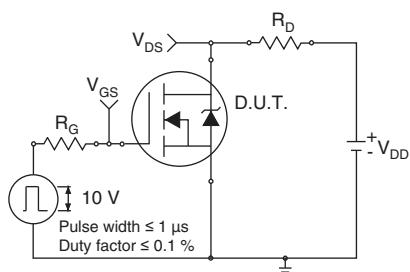


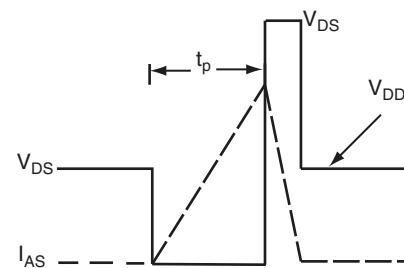
Fig. 9 - Maximum Safe Operating Area



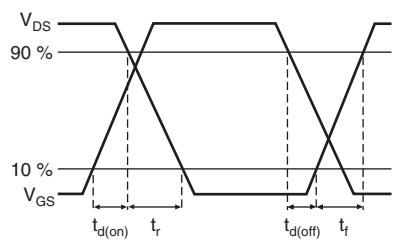
**Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case**



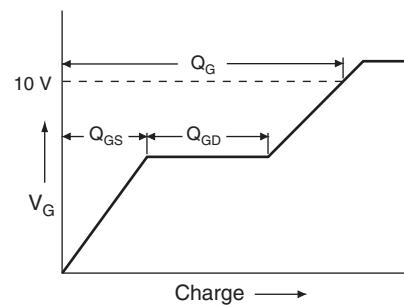
**Fig. 13 - Switching Time Test Circuit**



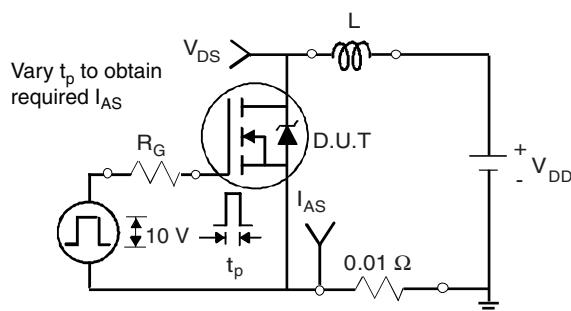
**Fig. 16 - Unclamped Inductive Waveforms**



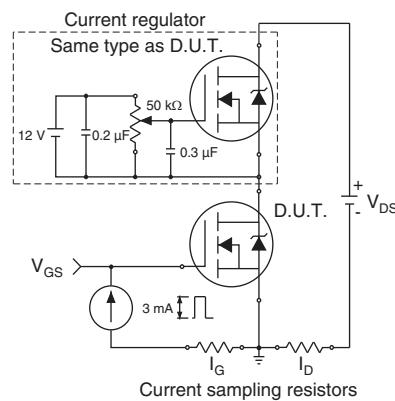
**Fig. 14 - Switching Time Waveforms**



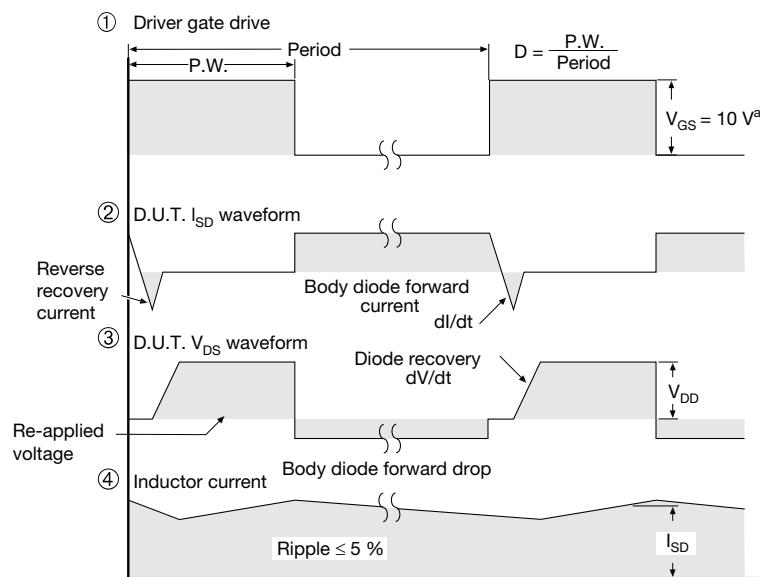
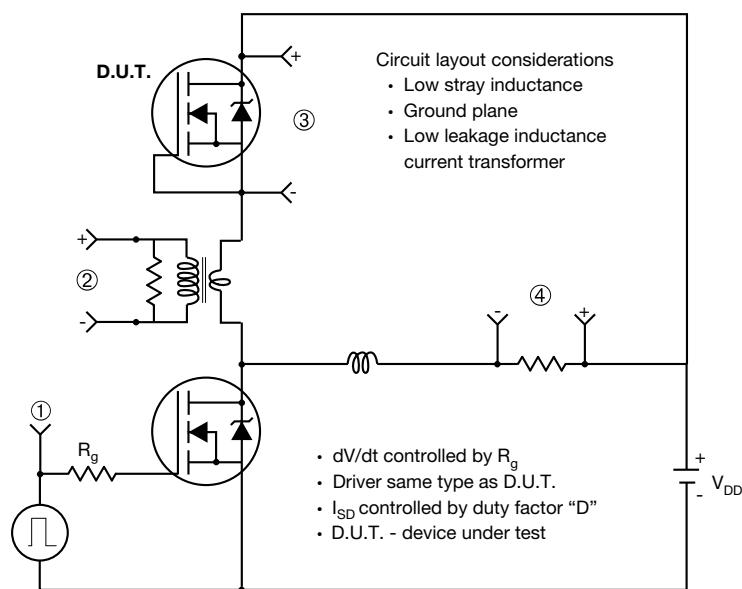
**Fig. 17 - Basic Gate Charge Waveform**



**Fig. 15 - Unclamped Inductive Test Circuit**

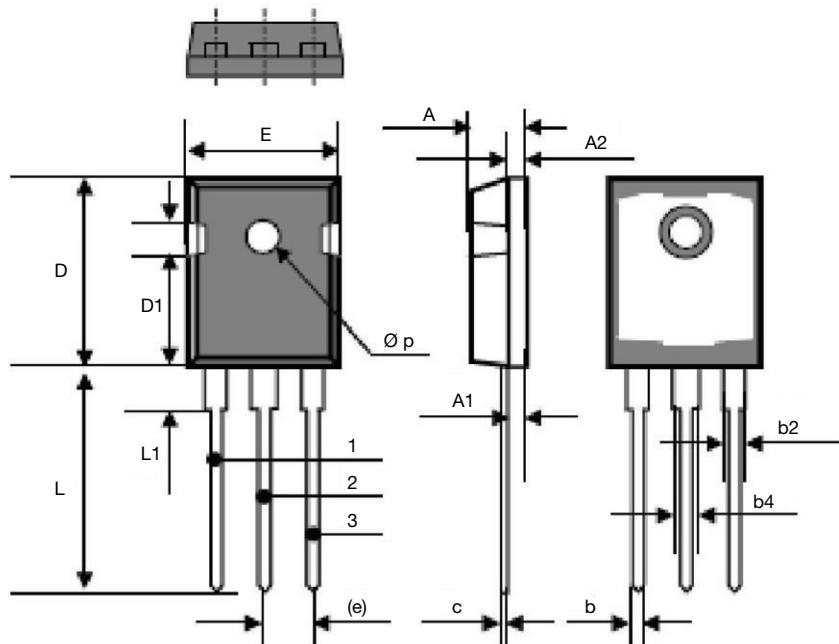


**Fig. 18 - Gate Charge Test Circuit**

**Peak Diode Recovery dV/dt Test Circuit**

**Fig. 19 - For N-Channel**

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## TO-247AD (High Voltage)



DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	4.70	5.31	0.185	0.209
A1	2.21	2.59	0.087	0.102
A2	1.50	2.49	0.059	0.098
b	0.99	1.40	0.039	0.055
b2	1.65	2.41	0.065	0.095
b4	2.59	3.43	0.102	0.135
c	0.61 BSC		0.024 BSC	
D	20.80	21.46	0.819	0.845
D1	3.68	5.49	0.145	0.216
(e)	5.46 BSC		0.215 BSC	
E	15.49	16.26	0.610	0.640
L	19.81	20.32	0.780	0.800
L1	4.06	4.50	0.160	0.177
Øp	3.51	3.66	0.138	0.144

ECN: S17-0178-Rev. B, 06-Feb-17  
DWG: 6010

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